74HC7541; 74HCT7541

Octal Schmitt trigger buffer/line driver; 3-state

Rev. 3 — 25 July 2011 Product data sheet

1. General description

The 74HC7541; 74HCT7541 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). It is specified in compliance with JEDEC standard No. 7A.

The 74HC7541; 74HCT7541 provides eight non-inverting buffer/line drivers with 3-state outputs and Schmitt-trigger action. The 3-state outputs are controlled by the output enable inputs $\overline{OE}1$ and $\overline{OE}2$. A HIGH on $\overline{OE}n$ causes the outputs to assume a high-impedance OFF-state. Schmitt trigger action on the data inputs transforms slowly changing input signals into sharply defined, jitter-free output signals.

The 74HC7541; 74HCT7541 is identical to the 74HC541; 74HCT541 but has hysteresis on the data inputs.

2. Features and benefits

- Non-inverting outputs
- Low-power dissipation
- ESD protection:
  - HBM JESD22-A114F exceeds 2000 V
  - MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from −40 °C to +85 °C and from −40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC7541N	−40 °C to +125 °C	DIP20	plastic dual in-line package; 20 leads (300 mil)	SOT146-1
74HCT7541N				
74HC7541D	−40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74HCT7541D				
74HC7541DB	−40 °C to +125 °C	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1
74HC7541PW	−40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74HCT7541PW				

4. Functional diagram

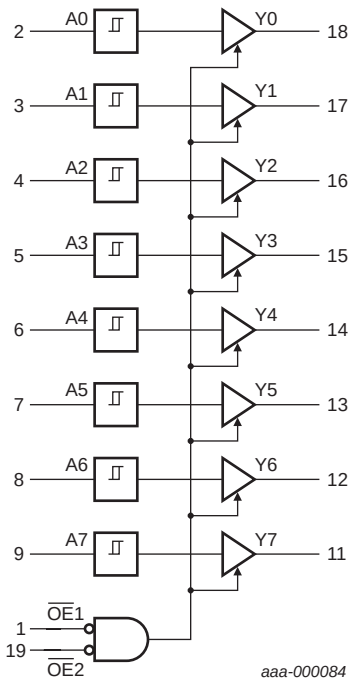

Fig 1. Logic symbol

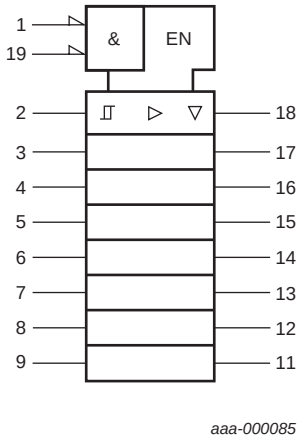

Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning

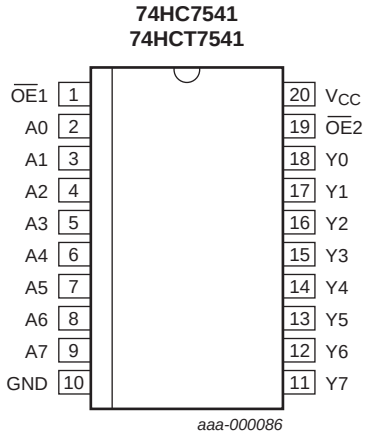

Fig 3. Pin configuration DIP20, SO20

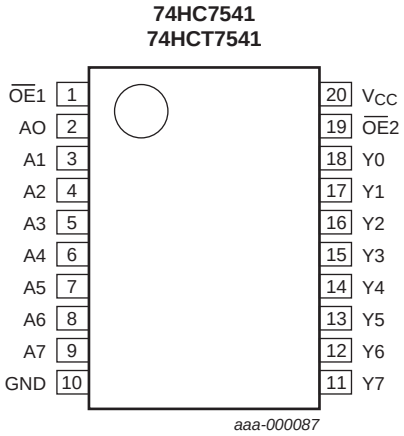

Fig 4. Pin configuration SSOP20, TSSOP20

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5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{OE}1$	1	output enable input (active LOW)
A0 to A7	2, 3, 4, 5, 6, 7, 8, 9	data input
GND	10	ground (0 V)
Y0 to Y7	18, 17, 16, 15, 14, 13, 12, 11	data output
$\overline{OE}2$	19	output enable input (active LOW)
V_{CC}	20	supply voltage

6. Functional description

Table 3. Functional table[1]

Control		Input	Output
$\overline{OE}1$	$\overline{OE}2$	An	Yn
L	L	L	L
L	L	H	H
X	H	X	Z
H	X	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			–0.5	+7	V
I_{IK}	input clamping current	$V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V	[1]	-	±20	mA
I_{OK}	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	[1]	-	±20	mA
I_O	output current	-0.5 V $< V_O < V_{CC} + 0.5$ V		-	±25	mA
I_{CC}	supply current			-	50	mA
I_{GND}	ground current			–50	-	mA
T_{stg}	storage temperature			–65	+150	°C
P_{tot}	total power dissipation		[2]			
	DIP20			-	750	mW
	SO20, SSOP20, TSSOP20			-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For DIP20 packages: above 70 °C the value of P_{tot} derates linearly with 12 mW/K.
For SO20 packages: above 70 °C the value of P_{tot} derates linearly with 8 mW/K.
For SSOP20 and TSSOP20 packages: above 60 °C the value of P_{tot} derates linearly with 5.5 mW/K.

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8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC7541			74HCT7541			Unit
			Min	Typ	Max	Min	Typ	Max	
V_{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V_I	input voltage		0	-	V_{CC}	0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	0	-	V_{CC}	V
T_{amb}	ambient temperature		−40	+25	+125	−40	+25	+125	°C

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T_{amb} = 25 °C			T_{amb} = −40 °C to +85 °C		T_{amb} = −40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC7541										
V_{OH}	HIGH-level output voltage	$V_I = V_{T+}$ or V_{T-}								
		I_O = −20 μA; V_{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I_O = −20 μA; V_{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = −20 μA; V_{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I_O = −6.0 mA; V_{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I_O = −7.8 mA; V_{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{T+}$ or V_{T-}								
		I_O = 20 μA; V_{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 20 μA; V_{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 20 μA; V_{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I_O = 6.0 mA; V_{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I_O = 7.8 mA; V_{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; V_{CC} = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; I_O = 0 A; V_{CC} = 6.0 V	-	-	8.0	-	80	-	160	μA
C_I	input capacitance		-	3.5	-	-	-	-	-	pF
74HCT7541										
V_{OH}	HIGH-level output voltage	$V_I = V_{T+}$ or V_{T-}; V_{CC} = 4.5 V								
		I_O = −20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I_O = −6.0 mA	3.98	4.32	-	3.84	-	3.7	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{T+}$ or V_{T-}; V_{CC} = 4.5 V								
		I_O = 20 μA;	-	0	0.1	-	0.1	-	0.1	V
		I_O = 6.0 mA;	-	0.15	0.26	-	0.33	-	0.4	V

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Table 6. Static characteristics *...continued*

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T_{amb} = 25 °C			T_{amb} = −40 °C to +85 °C		T_{amb} = −40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I_I	input leakage current	V_I = V_{CC} or GND; V_{CC} = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	µA
I_{CC}	supply current	V_I = V_{CC} or GND; I_O = 0 A; V_{CC} = 5.5 V	-	-	8.0	-	80	-	160	µA
ΔI_{CC}	additional supply current	per input pin; I_O = 0 A; V_I = V_{CC} − 2.1 V; other inputs at V_{CC} or GND; V_{CC} = 4.5 V to 5.5 V								
		An input	-	20	72	-	90	-	98	µA
		OEn input	-	130	468	-	585	-	637	µA
C_I	input capacitance		-	3.5	-	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

GND = 0 V; C_L = 50 pF; for test circuit see Figure 7.

Symbol	Parameter	Conditions		T_{amb} = 25 °C			T_{amb} = −40 °C to +125 °C		Unit
				Min	Typ	Max	Max (85 °C)	Max (125 °C)	
74HC7541									
t_{pd}	propagation delay	An to Yn; see Figure 5	[1]						
		V_{CC} = 2.0 V		-	39	120	150	180	ns
		V_{CC} = 4.5 V		-	14	24	30	36	ns
		V_{CC} = 5.0 V; C_L = 15 pF		-	10	-	-	-	ns
		V_{CC} = 6.0 V		-	11	20	26	32	ns
t_{en}	enable time	$\overline{OE}$n to Yn; see Figure 6	[1]						
		V_{CC} = 2.0 V		-	44	160	200	240	ns
		V_{CC} = 4.5 V		-	16	32	40	48	ns
		V_{CC} = 6.0 V		-	13	27	34	41	ns
t_{dis}	disable time	$\overline{OE}$n to Yn; see Figure 6	[1]						
		V_{CC} = 2.0 V		-	58	160	200	240	ns
		V_{CC} = 4.5 V		-	21	32	40	48	ns
		V_{CC} = 6.0 V		-	17	27	34	41	ns
t_t	transition time	see Figure 5	[2]						
		V_{CC} = 2.0 V		-	14	60	75	90	ns
		V_{CC} = 4.5 V		-	5	12	15	18	ns
		V_{CC} = 6.0 V		-	4	10	13	15	ns
C_{PD}	power dissipation capacitance	per package; V_I = GND to V_{CC}	[3]	-	30	-	-	-	pF

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Table 7. Dynamic characteristics

GND = 0 V; C_L = 50 pF; for test circuit see Figure 7.

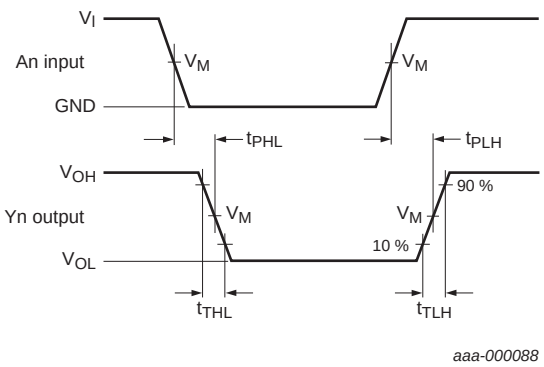
Symbol	Parameter	Conditions		T_{amb} = 25 °C			T_{amb} = −40 °C to +125 °C		Unit
				Min	Typ	Max	Max (85 °C)	Max (125 °C)	
74HCT7541									
t_{pd}	propagation delay	An to Yn; see Figure 5	[1]						
		V_{CC} = 4.5 V		-	19	32	40	48	ns
		V_{CC} = 5.0 V; C_L = 15 pF		-	16	-	-	-	ns
t_{en}	enable time	$\overline{OE}$n to Yn; see Figure 6	[1]						
		V_{CC} = 4.5 V		-	18	32	40	48	ns
t_{dis}	disable time	$\overline{OE}$n to Yn; see Figure 6	[1]						
		V_{CC} = 4.5 V		-	20	32	40	48	ns
t_t	transition time	V_{CC} = 4.5 V; see Figure 5	[2]	-	5	12	15	18	ns
C_{PD}	power dissipation capacitance	per package; V_I = GND to V_{CC} − 1.5 V	[3]	-	32	-	-	-	pF

[1] t_{pd} is the same as t_{PLH} and t_{PHL}.
t_{en} is the same as t_{PZL} and t_{PZH}.
t_{dis} is the same as t_{PLZ} and t_{PHZ}.

[2] t_t is the same as t_{THL} and t_{TLH}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in V;
N = number of inputs switching;
$\sum (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 5. Input to output propagation delays

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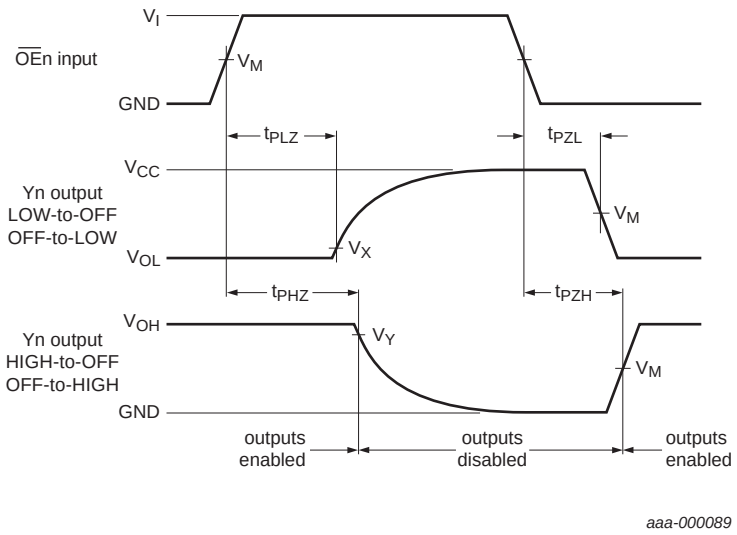

Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. 3-state enable and disable times

Table 8. Measurement points

Type	Input	Output		
	V_M	V_M	V_X	V_Y
74HC7541	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT7541	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$

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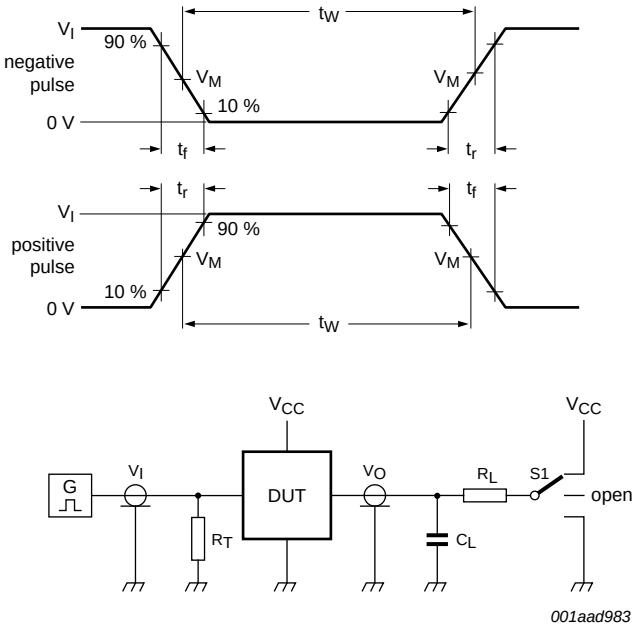

Test data is given in Table 9.

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator

C_L = Load capacitance including jig and probe capacitance

R_L = Load resistance

S1 = Test selection switch

Fig 7. Test circuit for measuring switching times

Table 9. Test data

Type	Input		Load		S1 position		
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
74HC7541	V_{CC}	6 ns	15 pF, 50 pF	1 kΩ	open	GND	V_{CC}
74HCT7541	3 V	6 ns	15 pF, 50 pF	1 kΩ	open	GND	V_{CC}

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12. Transfer characteristics

Table 10. Transfer characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); see Figure 8 and Figure 9.

Symbol	Parameter	Conditions	T_{amb} = 25 °C			T_{amb} = −40 °C to +85 °C		T_{amb} = −40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC7541										
V_{T+}	positive-going threshold voltage	V_{CC} = 2.0 V	-	-	1.5	-	1.5	-	1.5	V
		V_{CC} = 4.5 V	-	-	3.15	-	3.15	-	3.15	V
		V_{CC} = 6.0 V	-	-	4.2	-	4.2	-	4.2	V
V_{T-}	negative-going threshold voltage	V_{CC} = 2.0 V	0.3	-	-	0.3	-	0.3	-	V
		V_{CC} = 4.5 V	1.35	-	-	1.35	-	1.35	-	V
		V_{CC} = 6.0 V	1.8	-	-	1.8	-	1.8	-	V
V_H	hysteresis voltage	V_{CC} = 2.0 V	0.1	0.20	-	0.1	-	0.1	-	V
		V_{CC} = 4.5 V	0.25	0.40	-	0.25	-	0.25	-	V
		V_{CC} = 6.0 V	0.3	0.5	-	0.3	-	0.3	-	V
74HCT7541										
V_{T+}	positive-going threshold voltage	V_{CC} = 4.5 V	-	-	2.0	-	2.0	-	2.0	V
		V_{CC} = 5.5 V	-	-	2.1	-	2.1	-	2.1	V
V_{T-}	negative-going threshold voltage	V_{CC} = 4.5 V	0.7	-	-	0.64	-	0.6	-	V
		V_{CC} = 5.5 V	0.8	-	-	0.74	-	0.7	-	V
V_H	hysteresis voltage	V_{CC} = 4.5 V	0.17	0.23	-	-	-	-	-	V
		V_{CC} = 5.5 V	0.17	0.23	-	-	-	-	-	V

13. Transfer characteristics waveforms

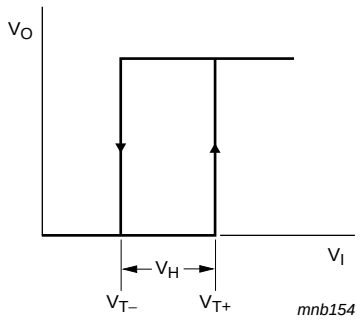

Fig 8. Transfer characteristics

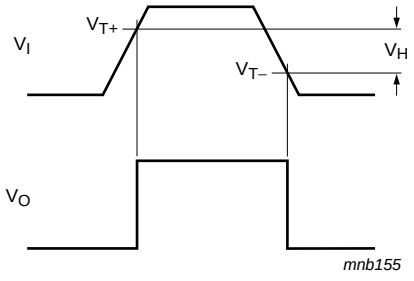

Fig 9. Transfer characteristics definitions

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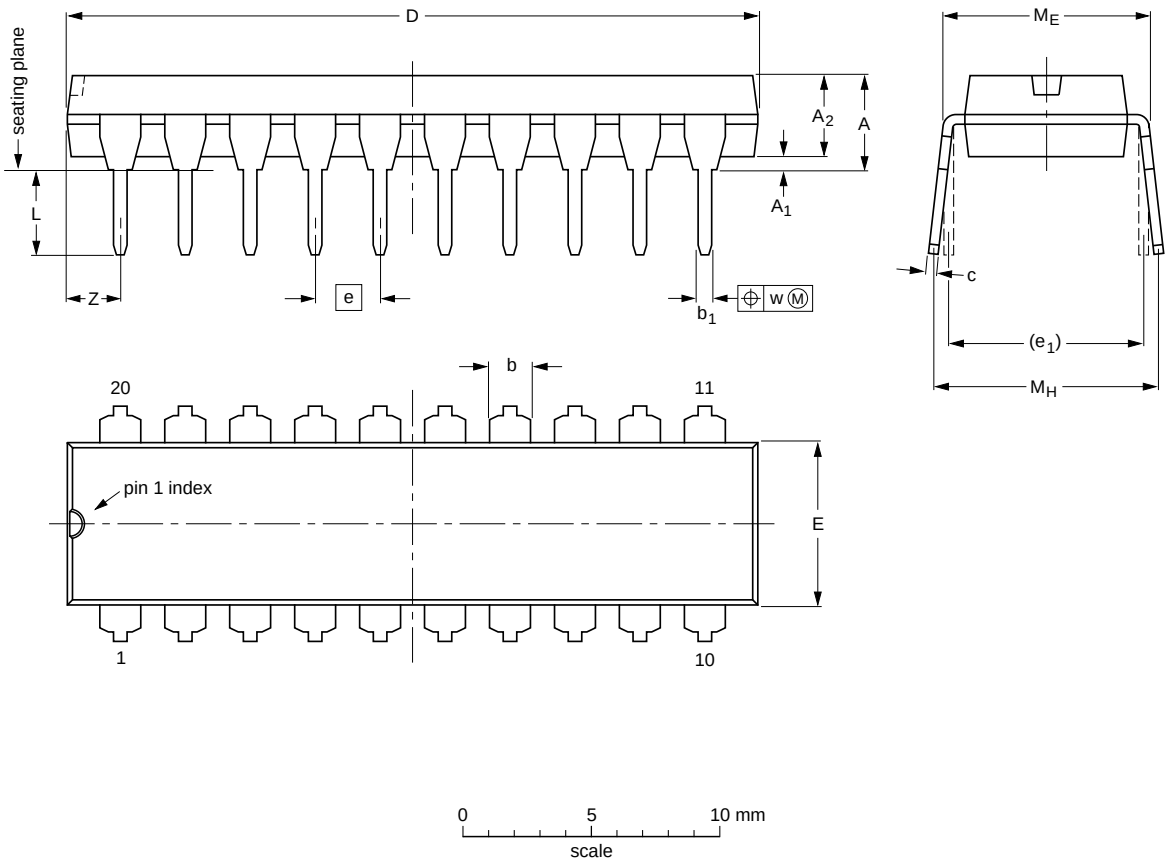
14. Package outline

DIP20: plastic dual in-line package; 20 leads (300 mil) **SOT146-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2
inches	0.17	0.02	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT146-1		MS-001	SC-603			~~99-12-27~~ 03-02-13

Fig 10. Package outline SOT146-1 (DIP20)

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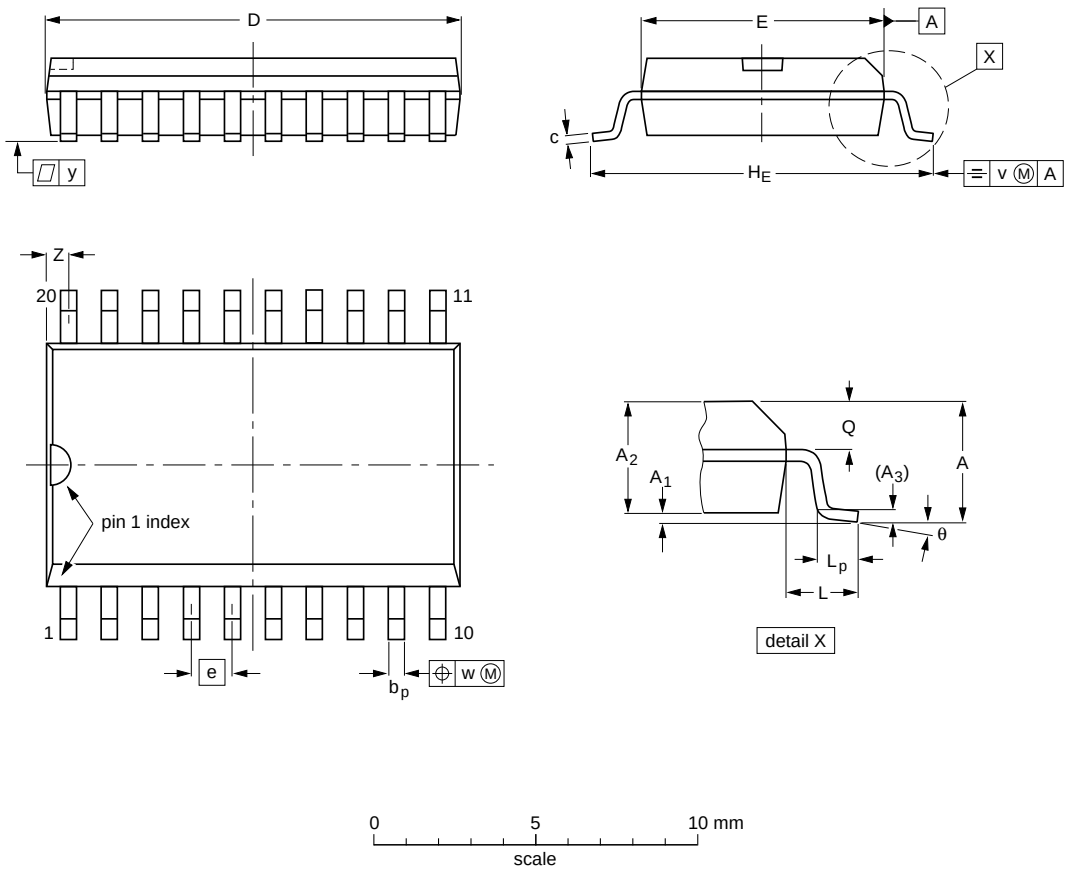
SO20: plastic small outline package; 20 leads; body width 7.5 mm **SOT163-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8^o 0^o
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				~~99-12-27~~ 03-02-19

Fig 11. Package outline SOT163-1 (SO20)

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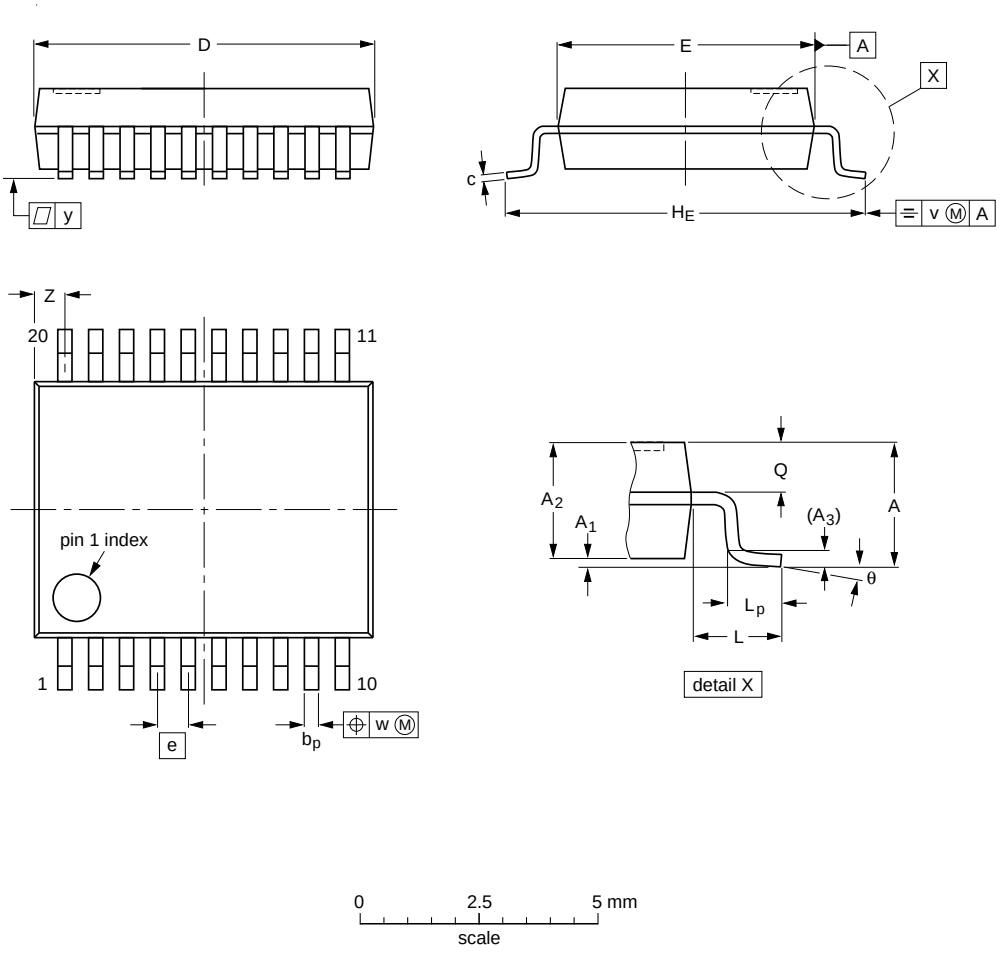
SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm **SOT339-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8^o 0^o

Note

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT339-1		MO-150				~~99-12-27~~ 03-02-19

Fig 12. Package outline SOT339-1 (SSOP20)

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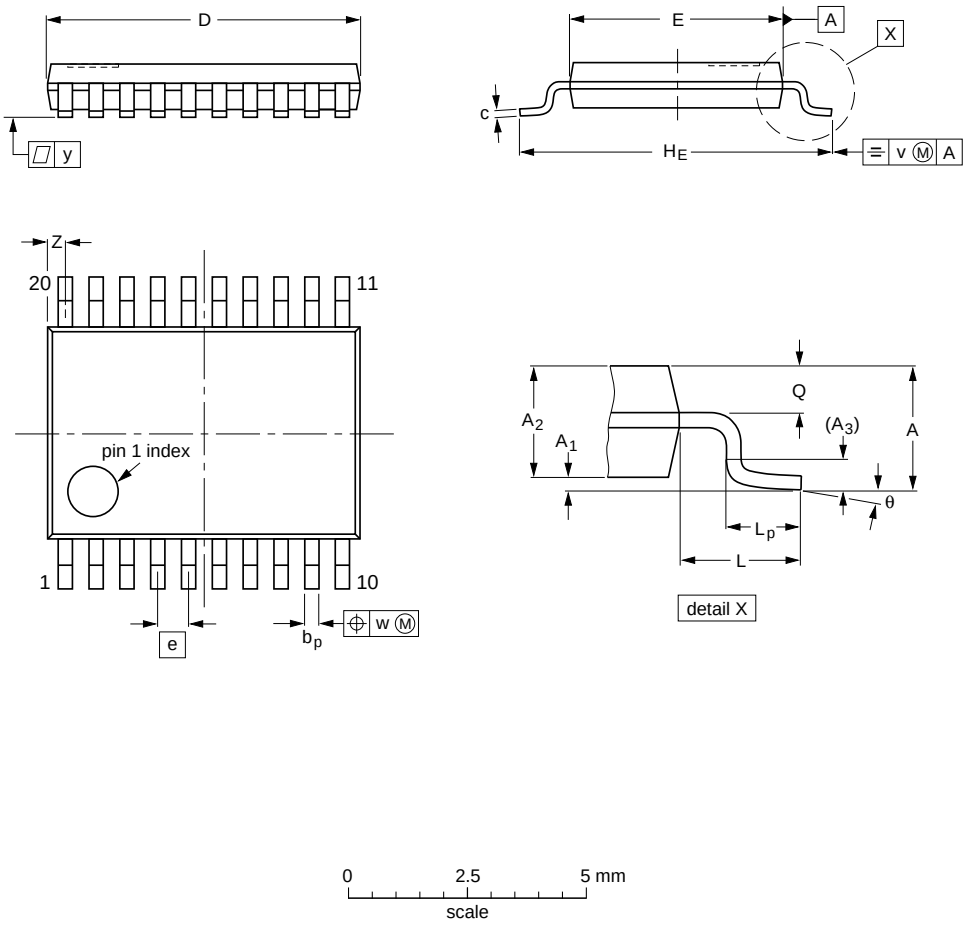
TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm **SOT360-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT360-1		MO-153				~~99-12-27~~ 03-02-19

Fig 13. Package outline SOT360-1 (TSSOP20)

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15. Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model

16. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT7541 v.3	20110725	Product data sheet	-	74HC_HCT7541_CNV v.2
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Added type numbers 74HC7541PW and 74HCT7541PW (TSSOP20 package).			
74HC_HCT7541_CNV v.2	19970917	Product specification	-	-

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17.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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